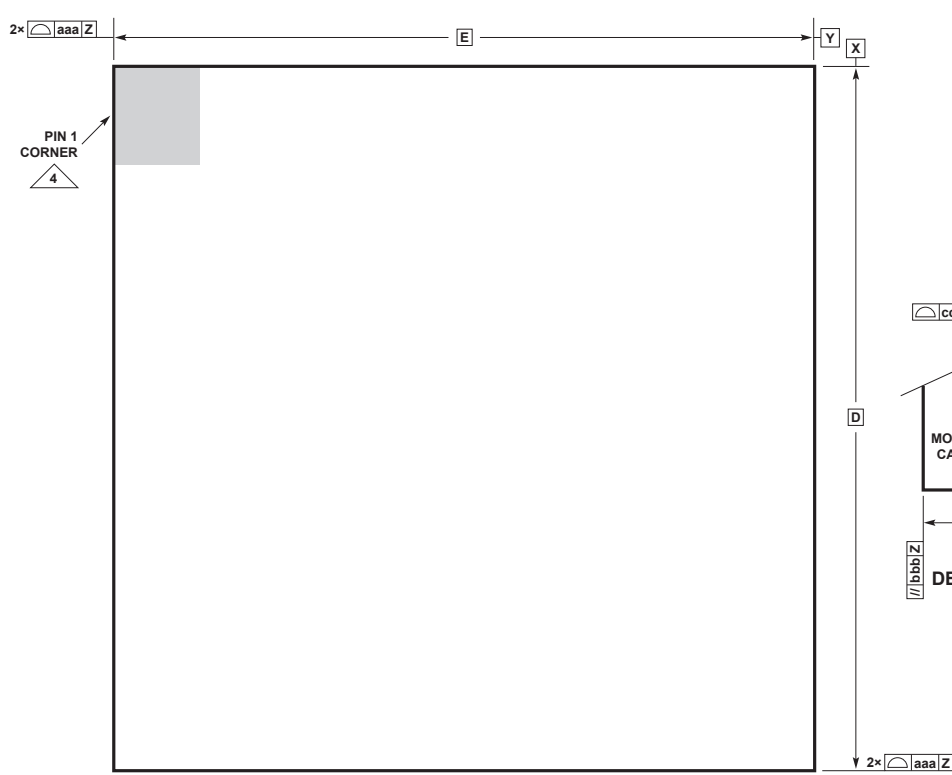
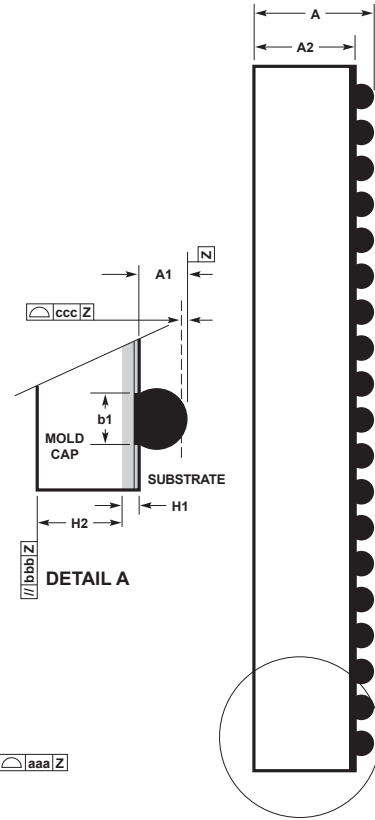


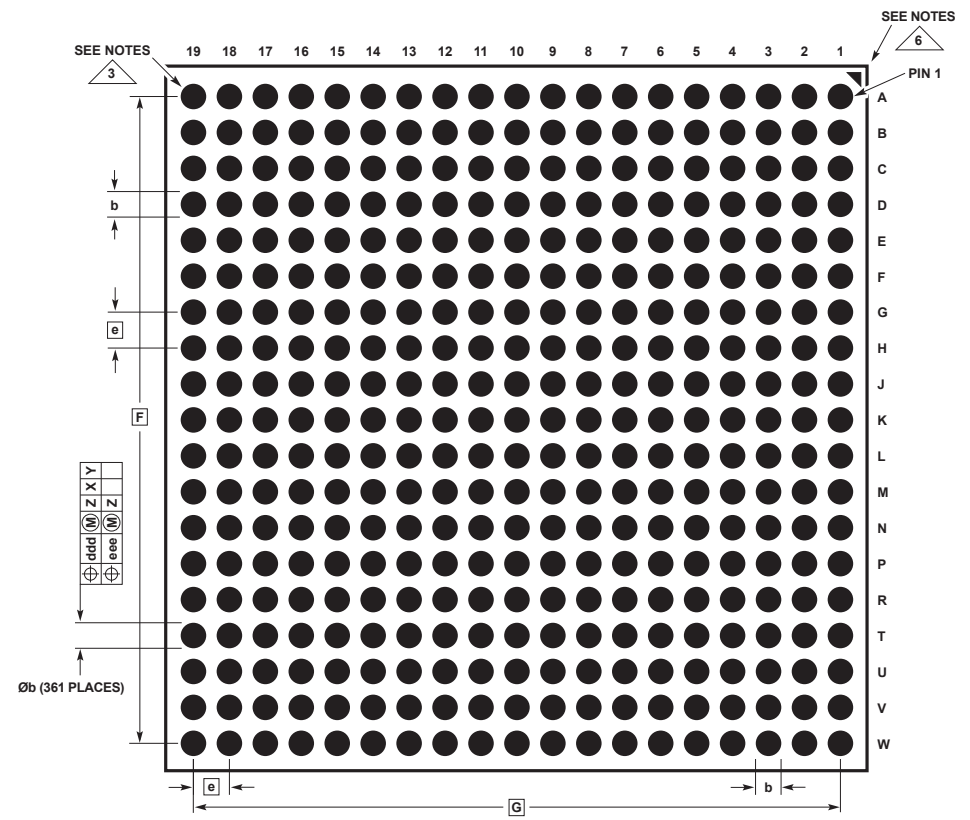
BGA Package
361-Lead (16mm × 16mm × 4.72mm)
 (Reference DWG# 05-08-1601)



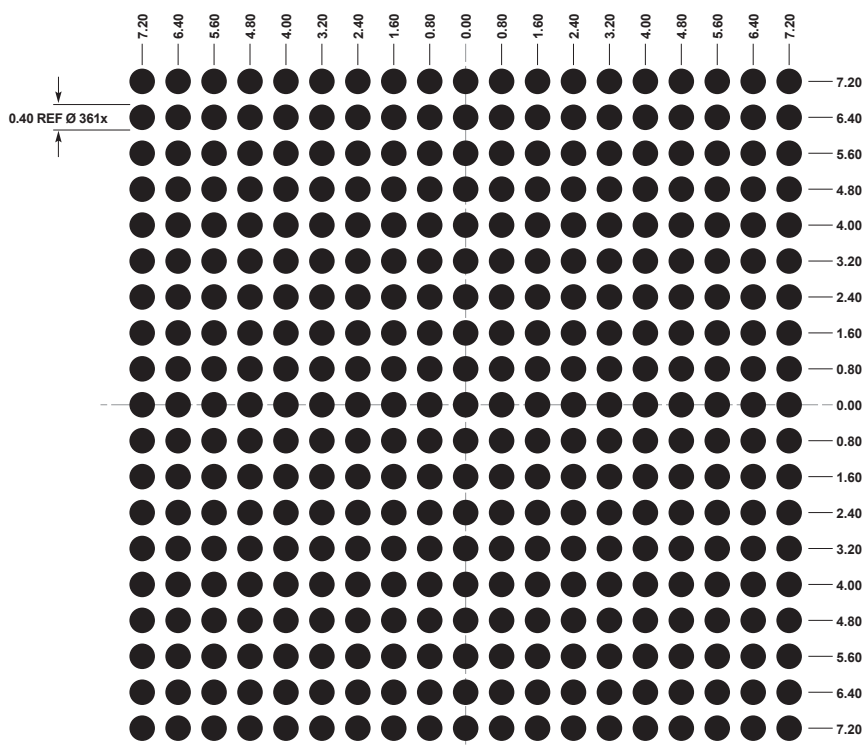
PACKAGE TOP VIEW



DETAIL A
 PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



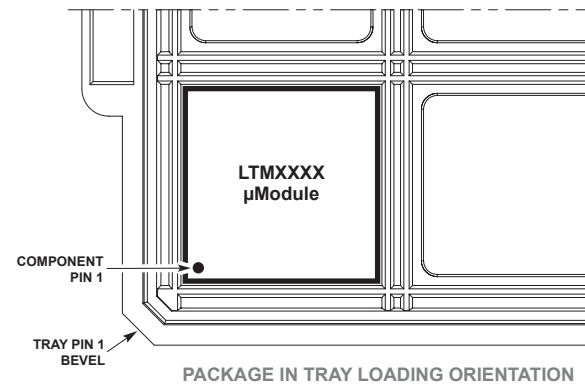
SUGGESTED PCB LAYOUT
 TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.53	4.72	4.91	
A1	0.30	0.40	0.50	BALL HT
A2	4.23	4.32	4.41	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D	16.00			
E	16.00			
e	0.80			
F	14.40			
G	14.40			
H1	0.32 REF			SUBSTRATE THK
H2	4.00 REF			MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 361

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION